

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Yung Fu (Alfred) Chong	02/08/2006
RECEIVING PARTY DATA	
Name:	Chartered Semiconductor Manufacturing, Ltd.
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11356666
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Total Attachments: 1 source=GRP-CPC_0309093714_001#page1.tif	

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ATTORNEY'S DOCKET NO.
2005 P 54583 US

ASSIGNMENT


WHEREAS, we the undersigned inventors, of residences as listed below, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, and

WHEREAS, Chartered Semiconductor Manufacturing, Ltd., having a principal place of business in Singapore, ("Assignee") desires to acquire our entire right, title and interest in and to the invention, and in and to said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for and in consideration of good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we assign to Assignee all right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, continuations, continuations-in-part and extensions thereof; and in and to any applications filed in any foreign country or group of countries based thereon, including the right to file said foreign applications and to claim priority under the provisions of the International convention and any other relevant convention or treaty; and we hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as our interest is concerned, to Assignee.

We also assign to Assignee, all right, title and interest to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents and legal equivalents, including utility models, industrial models and designs for said inventions in its own name throughout the world including all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and we further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such right, title and interest in Assignee.

We will communicate to Assignee any facts known to us respecting any improvements; and, at the expense of Assignee, we will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, make lawful oaths and declarations and generally take all reasonable steps to vest title in Assignee and to aid Assignee to obtain and enforce proper protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;			
TITLE OF INVENTION	Semiconductor Devices and Methods of Manufacturing Thereof		
SIGNATURE OF INVENTOR AND NAME	(1) Yung Fu (Alfred) Chong 		
DATE	2/8/06		
RESIDENCE (CITY AND STATE)	Singapore		

Assignment of Invention
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